

ABSTRACT OF THE DISCLOSURE

In the present invention, the problem that when the conventional semiconductor container opening/closing apparatus opens a lid of a semiconductor container, foreign particles enter into the semiconductor container from outside through a gap between the semiconductor container and a wall surface of the semiconductor container opening/closing apparatus and adhere to a wafer is solved. As a result, the number of foreign particles adhering to the wafer is reduced by preventing foreign particles from entering into the container at the time of opening the semiconductor container by the semiconductor container opening/closing apparatus.

In the semiconductor container opening/closing apparatus according to the present invention, a velocity-differential pressure ratio obtained by dividing the maximum velocity at the time of opening the lid of the semiconductor container in a vertical direction to an opening of the semiconductor container, by the differential pressure between the inside pressure and the outside pressure of said semiconductor manufacturing apparatus, is set to be 0.06 ((m/s) Pa) or less.

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